

MURA115, MURA120, NRVUA120V, SURA8120

Surface Mount Ultrafast Power Rectifiers

Ideally suited for high voltage, high frequency rectification, or as free wheeling and protection diodes in surface mount applications where compact size and weight are critical to the system.

Features

- Small Compact Surface Mountable Package with J-Bend Leads
- Rectangular Package for Automated Handling
- High Temperature Glass Passivated Junction
- Low Forward Voltage Drop (0.71 V Max @ 1.0 A, $T_J = 150^\circ\text{C}$)
- NRVUA and SURA8 Prefixes for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant*

Mechanical Characteristics:

- Case: Epoxy, Molded
- Weight: 70 mg (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Polarity: Polarity Band Indicates Cathode Lead
- ESD Protection:
 - ♦ Human Body Model > 4000 V (Class 3)
 - ♦ Machine Model > 400 V (Class C)



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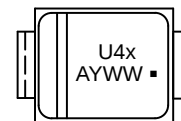
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ULTRAFAST RECTIFIERS 1 AMPERE, 100–200 VOLTS



SMA
CASE 403D

MARKING DIAGRAM



U4x = Device Code
x = C for MURA115
= D for MURA120
A = Assembly Location
Y = Year
WW = Work Week
▪ = Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping [†]
MURA115T3G	SMA (Pb-Free)	5,000/Tape & Reel
MURA120T3G	SMA (Pb-Free)	5,000/Tape & Reel
NRVUA120VT3G	SMA (Pb-Free)	5,000/Tape & Reel
SURA8120T3G	SMA (Pb-Free)	5,000/Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage MURA115T3G MURA120T3G/SURA8120T3G/NRVUA120VT3G	V_{RRM} V_{RWM} V_R	150 200	V
Average Rectified Forward Current @ $T_L = 155^\circ\text{C}$ @ $T_L = 135^\circ\text{C}$	$I_{F(AV)}$	1.0 2.0	A
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I_{FSM}	40	A
Operating Junction Temperature Range	T_J	-65 to +175	$^\circ\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Lead ($T_L = 25^\circ\text{C}$) (Note 1)	Ψ_{JL} (Note 2)	24	$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{\theta JA}$	216	

1. Rating applies when surface mounted on the minimum pad size recommended, PC Board FR-4.
2. In compliance with JEDEC 51, these values (historically represented by $R_{\theta JL}$) are now referenced as Ψ_{JL} .

ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Maximum Instantaneous Forward Voltage (Note 3) ($I_F = 1.0\text{ A}$, $T_J = 25^\circ\text{C}$) ($I_F = 1.0\text{ A}$, $T_J = 150^\circ\text{C}$)	V_F	0.875 0.71	V
Maximum Instantaneous Reverse Current (Note 3) (Rated DC Voltage, $T_J = 25^\circ\text{C}$) (Rated DC Voltage, $T_J = 150^\circ\text{C}$)	I_R	2.0 50	μA
Maximum Reverse Recovery Time ($I_F = 1.0\text{ A}$, $di/dt = 50\text{ A}/\mu\text{s}$)	t_{rr}	35	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Pulse Test: Pulse Width = 300 μs , Duty Cycle $\leq 2.0\%$.

TYPICAL CHARACTERISTICS

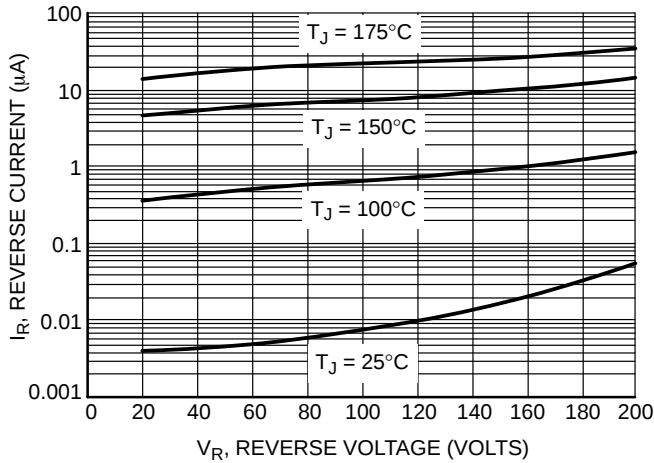


Figure 1. Typical Reverse Current

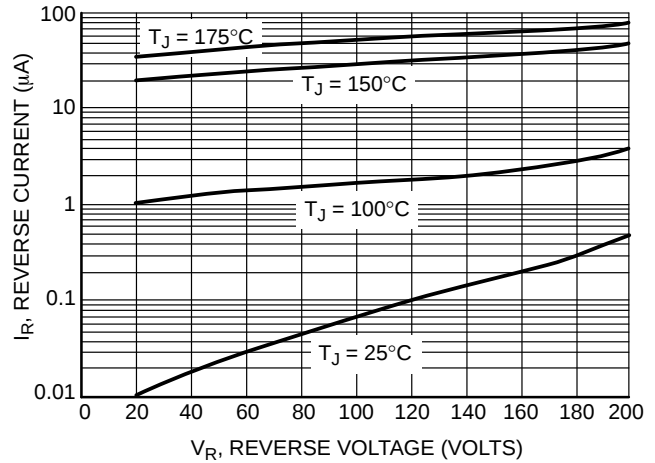


Figure 2. Maximum Reverse Current

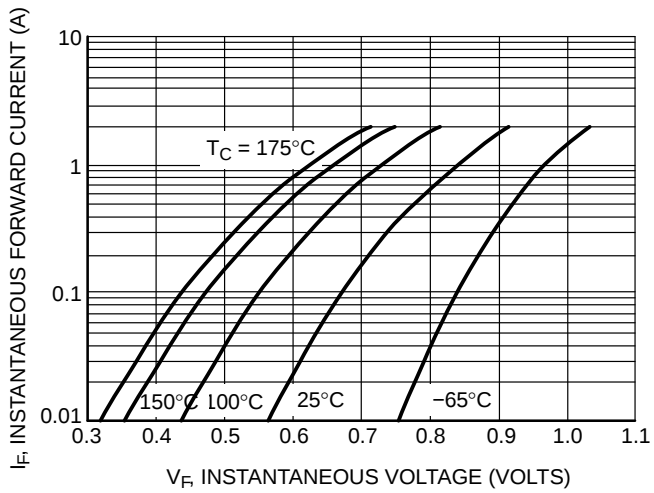


Figure 3. Typical Forward Voltage

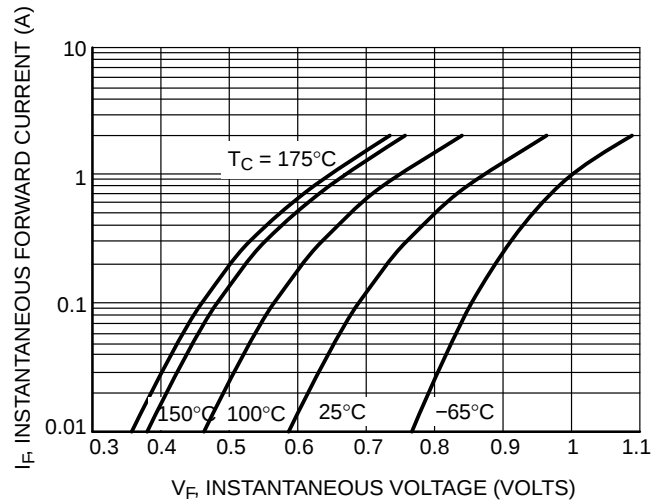


Figure 4. Maximum Forward Voltage

TYPICAL CHARACTERISTICS

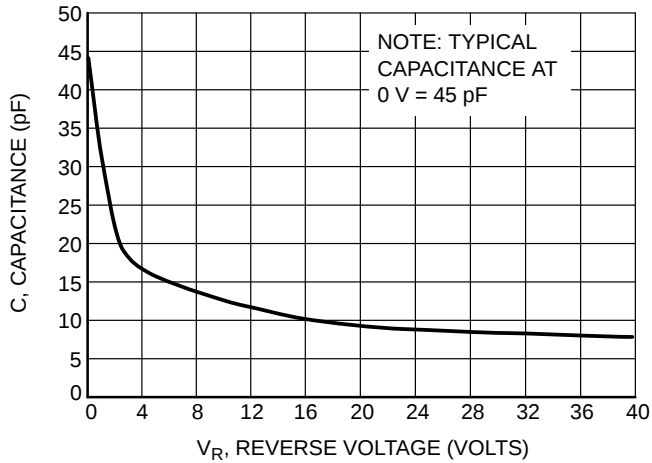


Figure 5. Typical Capacitance

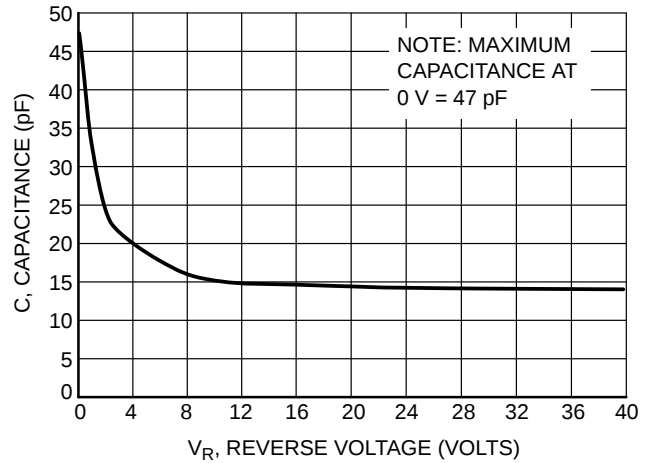


Figure 6. Maximum Capacitance

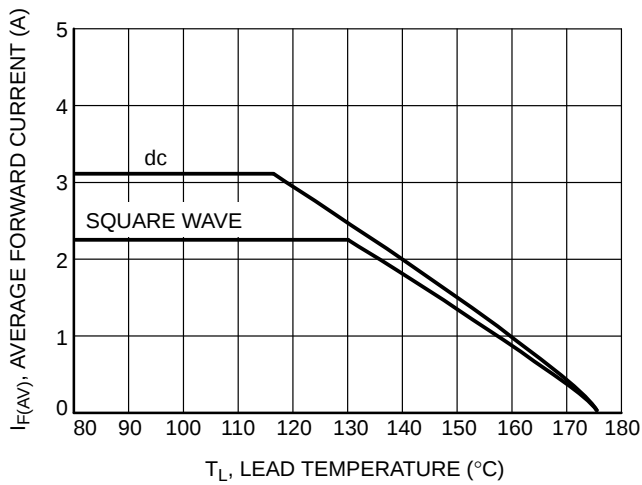


Figure 7. Current Derating, Lead

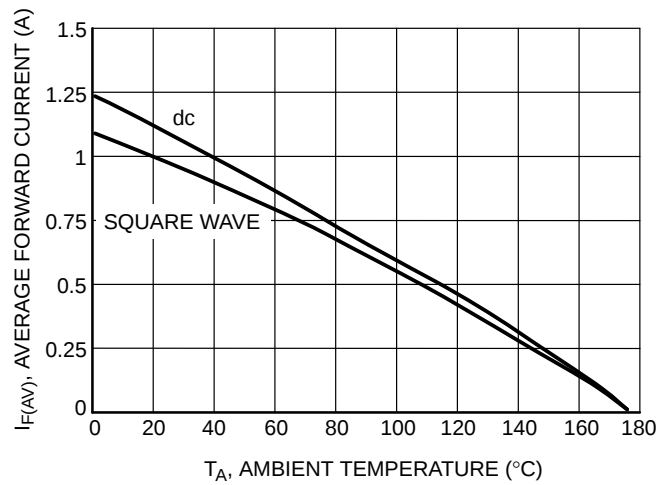


Figure 8. Current Derating, Ambient
(FR-4 Board with Minimum Pad)

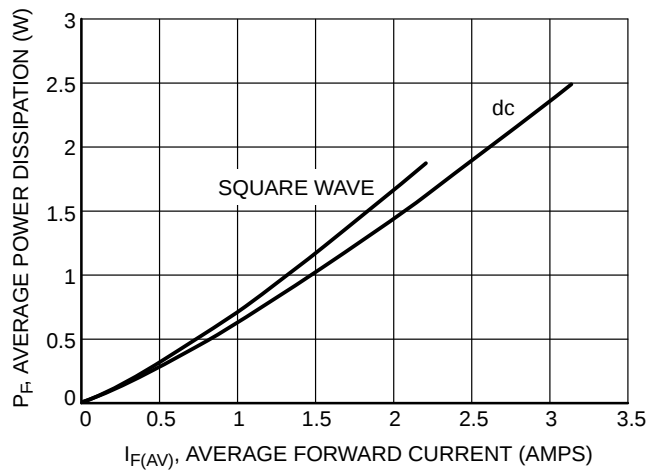


Figure 9. Power Dissipation

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®



STYLE 1

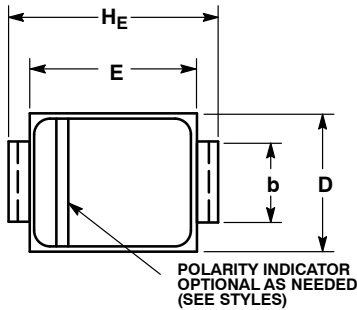


STYLE 2

SCALE 1:1

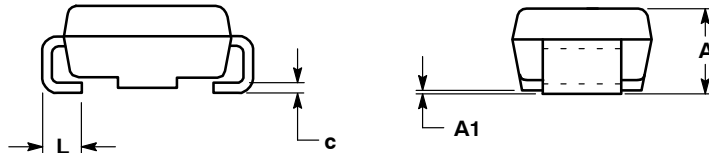
SMA CASE 403D ISSUE H

DATE 23 SEP 2015

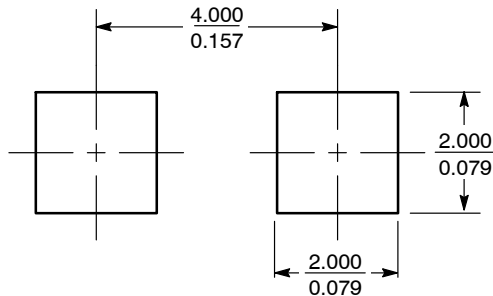


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION b SHALL BE MEASURED WITHIN DIMENSION L.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.97	2.10	2.20	0.078	0.083	0.087
A1	0.05	0.10	0.20	0.002	0.004	0.008
b	1.27	1.45	1.63	0.050	0.057	0.064
c	0.15	0.28	0.41	0.006	0.011	0.016
D	2.29	2.60	2.92	0.090	0.103	0.115
E	4.06	4.32	4.57	0.160	0.170	0.180
HE	4.83	5.21	5.59	0.190	0.205	0.220
L	0.76	1.14	1.52	0.030	0.045	0.060



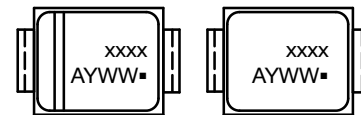
SOLDERING FOOTPRINT*



SCALE 8:1 (mm/inches)

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



STYLE 1

STYLE 2

xxxx = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
▪ = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

STYLE 1:
PIN 1. CATHODE (POLARITY BAND)
2. ANODE

STYLE 2:
NO POLARITY

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